

SimpleLink™ Wi-Fi® CC3000 Module from Texas Instruments

FEATURES

- **Wireless Network Processor**
 - IEEE 802.11 b/g
 - Embedded IPv4 TCP/IP Stack
- **Best-in-class Radio Performance:**
 - Tx Power: +18dBm at 11Mbps, CCK
 - Rx Sensitivity: –86dBm, 8% PER, 11Mbps
- **Works with low MIPS, Low Cost Microcontrollers with Compact Memory Footprint:**
 - 2KBytes Flash
 - 250Bytes RAM
- **FCC, IC and CE Certified with Chip Antenna**
- **HW Design Files and Design Guide Available from TI**
- **Integrated Crystal and Power Management**

- **Small Form Factor**
16.3mm x 13.5mm x 2mm
- **Operating Temperature Range:**
–20°C to 70°C
- **Based in TI's 7th Generation of Proven Wi-Fi Solutions**
- **Complete Platform Solution Including User and Porting Guides, API Guide, Sample Applications, and Support Community**

APPLICATIONS

- **Home Automation**
- **Home Security**
- **Connected Appliances**
- **Smart Energy**
- **M2M Communication**

DESCRIPTION

The CC3000 is a self-contained wireless network processor that simplifies the process of implementing Internet connectivity. SimpleLink™ Wi-Fi minimizes host microcontroller (MCU) software requirements making it the ideal solution for embedded applications using any low-cost and low-power MCU.

The CC3000 is provided as a module by TI to reduce development time, lower manufacturing costs, save board space, ease certification and minimize RF expertise required. Additionally, it is provided as a complete platform solution including software drivers, sample applications, API guide, user documentation and a world-class support community.

More information on TI's wireless platform solutions for Wi-Fi can be found on TI's Wireless Connectivity Wiki (www.ti.com/connectivitywiki).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
CC3000MOD	ACTIVE			46	84	TBD	Call TI	Call TI	-20 to 70		Samples
CC3000MODR	ACTIVE			46	1200	TBD	Call TI	Call TI	-20 to 70		Samples
XCC3000MOD	PREVIEW			46		TBD	Call TI	Call TI	-20 to 70		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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